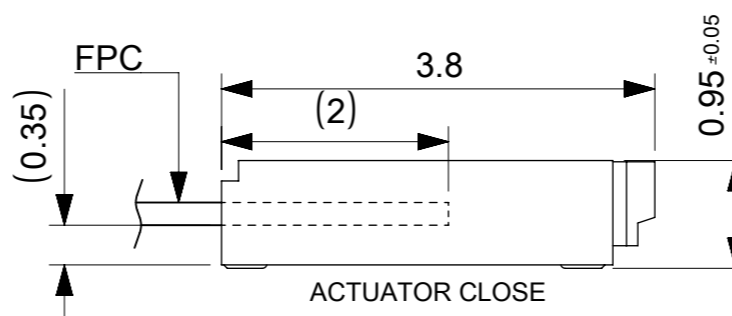
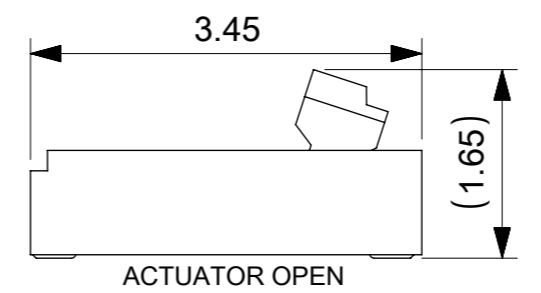
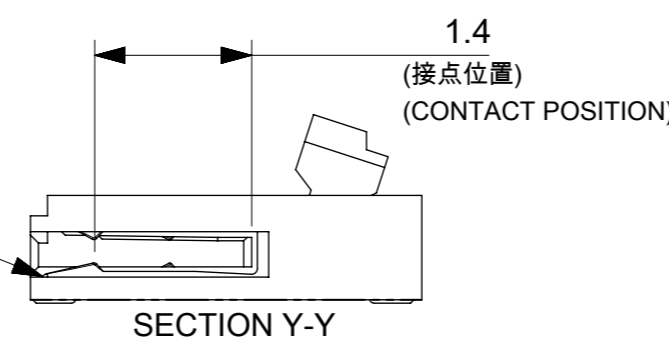
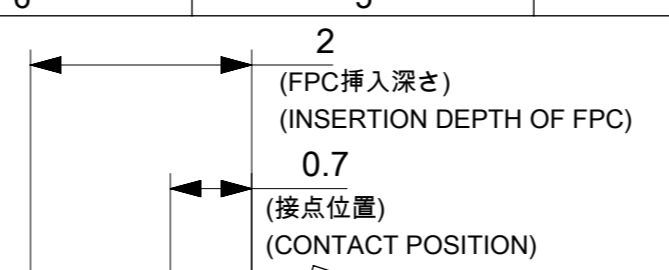


アクチュエータ
ACTUATOR
ハウジング
HOUSING
奇数極端子
ODD TERMINAL

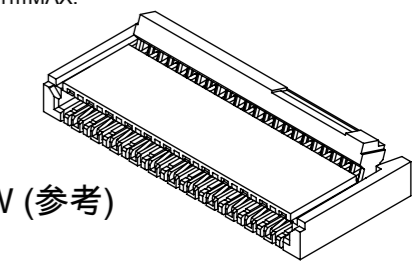
偶数極端子
EVEN TERMINAL



0.12 ±0.03
0.15 X

0.12 ±0.03
0.15 X

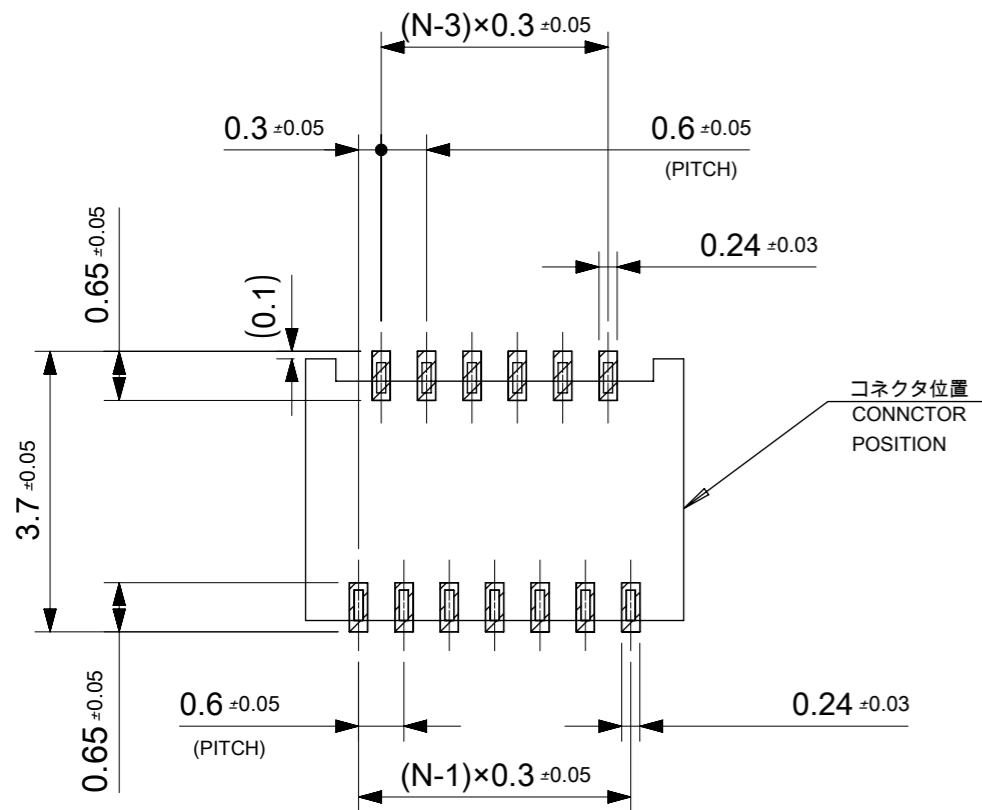
- 注記 NOTES
1. 使用材料 MATERIALS
 ハウジング : 液晶ポリマー(LCP)、ガラス充填、UL94 V-0、ナチュラル(白色系)
 アクチュエータ : ポリアミド(PA)、ガラス充填、UL94、HB、黒色
 奇数端子 : リン青銅 t=0.12mm
 偶数端子 : リン青銅 t=0.12mm
 HOUSING : LIQUID CRYSTAL POLYMER(LCP)、GLASS FILLED、UL94、V-0、NATURAL(WHITE)
 ACTUATOR : POLYIMIDE(PA)、GLASS FILLED、UL94、HB、BLACK
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
 2. メッキ仕様 PLATING
 端子 TERMINAL
 テール部 : 金メッキ
 接点部 : 金メッキ 0.1µm以上
 下地 : ニッケルメッキ 1.0µm以上
 TAIL AREA: Gold PLATING
 CONTACT AREA: Gold PLATING 0.1µm MINIMUM
 UNDER PLATING: Nickel PLATING 1.0µm MINIMUM
 3. 端子の平坦度は0.1mm以下とする
 COPLANALITY OF SOLDER TAILS: 0.1mm MAX.
 4. ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.8	6.6	7.2	8.6	504740-2500	25
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
3.6	2.4	3.0	4.4	504740-1100	11
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

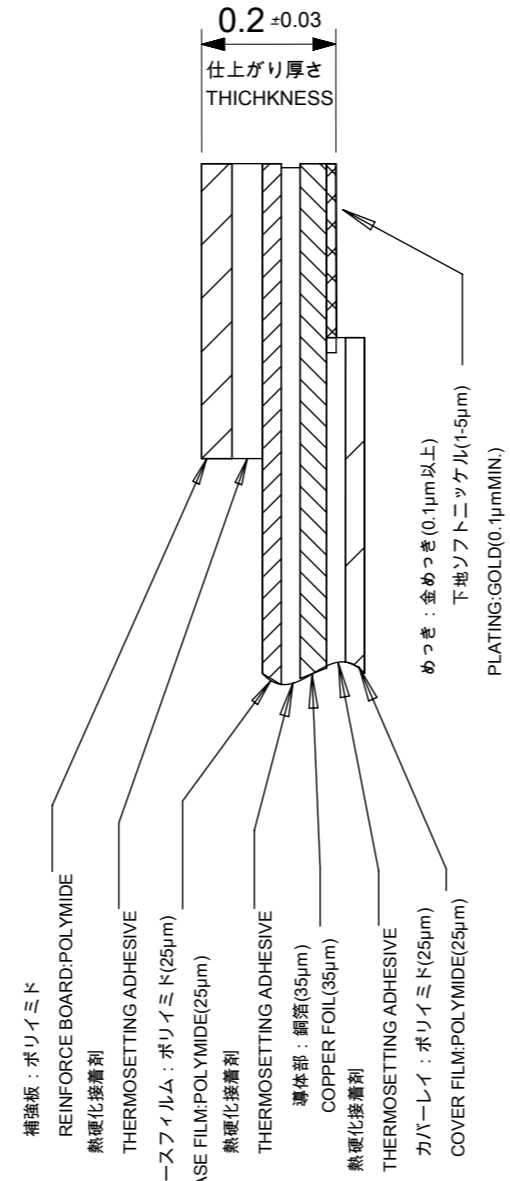
CONNECTOR SERIES NO. 504740-**09

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:		molex	
DIMENSION UNITS	SCALE				
mm	10:1			0.3 FPC CONN. BF H=0.95 HOUSING ASSY	
GENERAL TOLERANCES (UNLESS SPECIFIED)				PRODUCT CUSTOMER DRAWING	
ANGULAR TOL	± 1.0°			DOCUMENT NUMBER	
4 PLACES	± 0.03	EC NO: 646888		5047401000	
3 PLACES	± 0.03	DRWN: TNAKAGAWA01 2020/10/08		DOC TYPE	
2 PLACES	± 0.05	CHK'D: YMATSUMOTO 2020/10/14		PSD	
1 PLACE	± 0.1	APPR: SHOSHIKAWA 2020/10/14		DOC PART	
0 PLACES	± 0.2	INITIAL REVISION:		000	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRWN: SHIRATA 2015/03/03		C	
THIRD ANGLE PROJECTION		APPR: KMORIKAWA 2016/08/02		REVISION	
DRAWING		SERIES		SHEET NUMBER	
A3-SIZE		504740		1 OF 2	
MATERIAL NUMBER		CUSTOMER			
GENERAL					

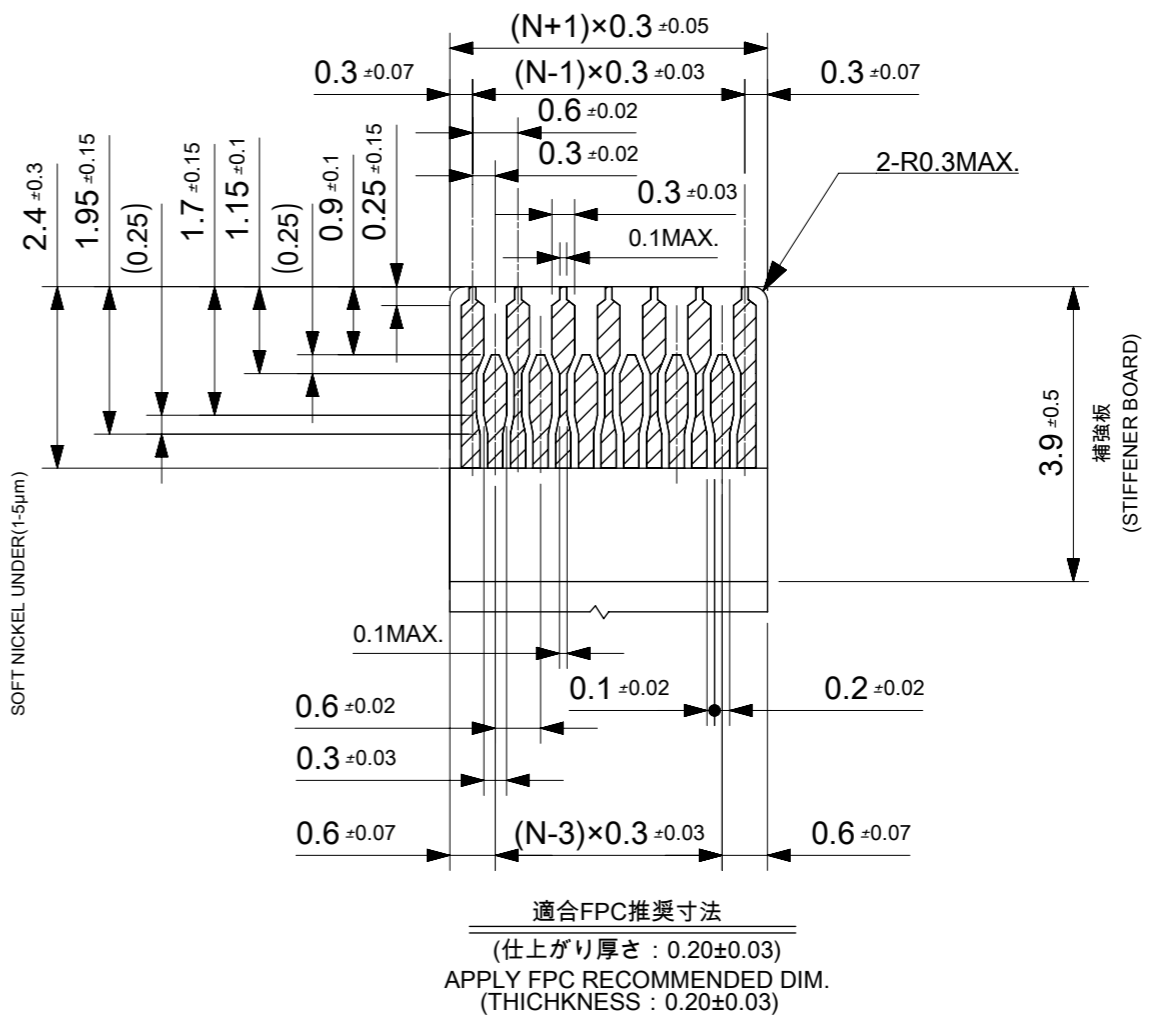


参照基板レイアウト(マウント面)
P.W. BOARD PATTERN
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm
RECOMMENDED METAL MASK THICKNESS : 0.1mm
推奨開口率 : 80%
APERTURE RATE : 80%



FPC構成推奨仕様
STRUCTURE OF FPC



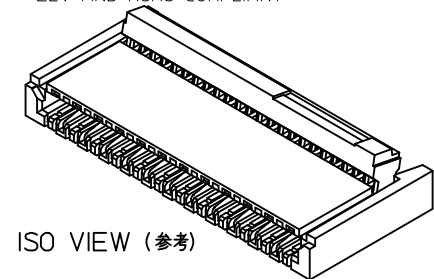
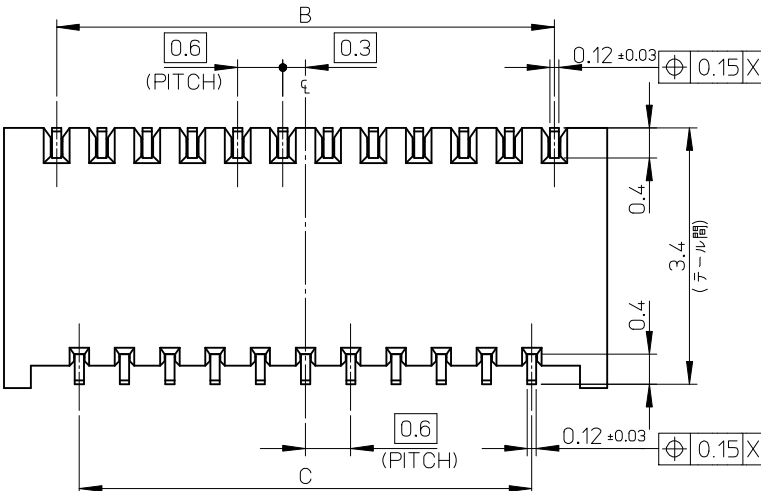
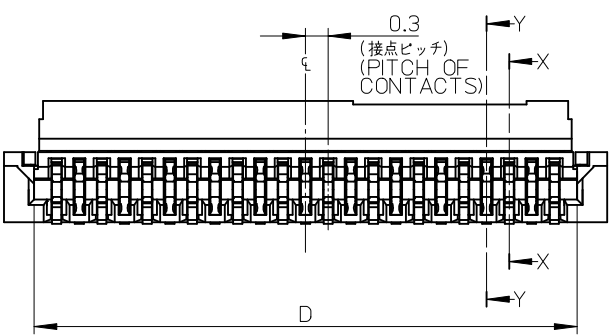
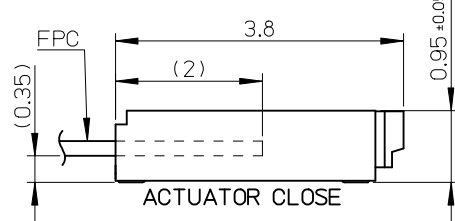
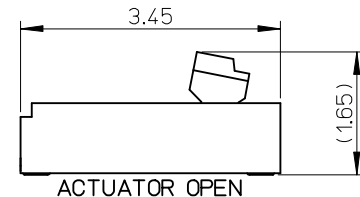
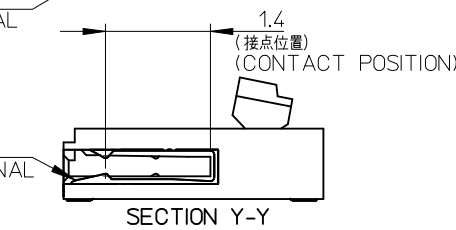
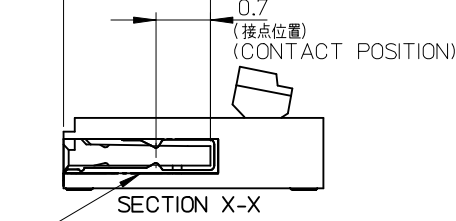
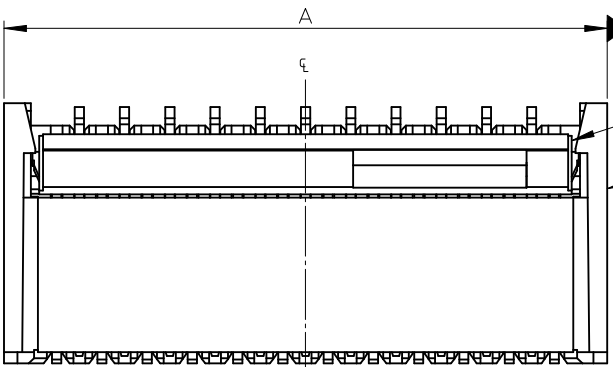
FPCについて (ABOUT FPC)
抜き方向は、導体側から補強版側を推奨致します。
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFNER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFNER BOARD AS 0.5mm MINIMUM.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:		molex	
DIMENSION UNITS	SCALE				
mm	1:1			0.3 FPC CONN. BF H=0.95 HOUSING ASSY	
GENERAL TOLERANCES (UNLESS SPECIFIED)					
ANGULAR TOL	± 1.0 °				
4 PLACES	± 0.03	EC NO: 646888			
3 PLACES	± 0.03	DRWN: TNAKAGAWA01	2020/10/08		
2 PLACES	± 0.05	CHK'D: YMATSUMOTO	2020/10/14		
1 PLACE	± 0.1	APPR: SHOSHIKAWA	2020/10/14		
0 PLACES	± 0.2	INITIAL REVISION:		DOCUMENT NUMBER	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRWN: SHIRATA	2015/03/03	5047401000	
THIRD ANGLE PROJECTION		APPR: KMORIKAWA	2016/08/02	DOC TYPE	DOC PART
DRAWING		SERIES		PSD	000
A3-SIZE		504740		REVISION	C
MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
GENERAL		GENERAL		2 OF 2	

注記 NOTES

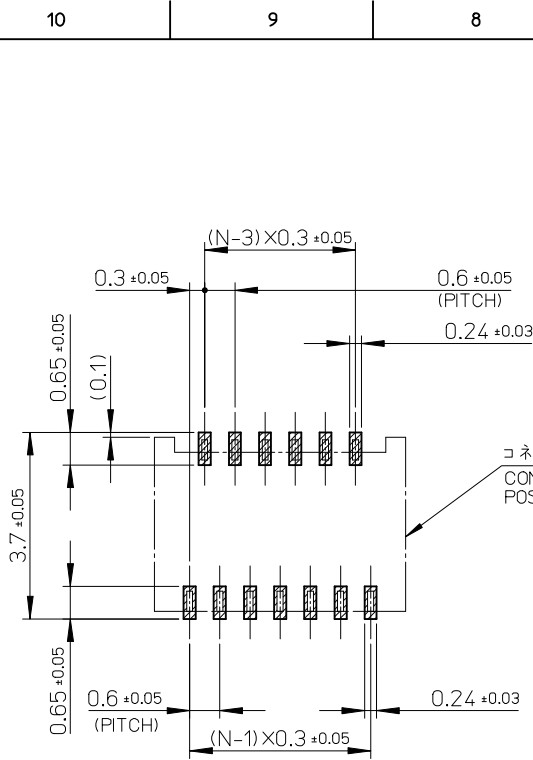
- 使用材料 MATERIALS
 ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94 V-0、ナチュラル (白色系)
 アクチュエータ: ポリアミド (PA)、ガラス充填、UL94 HB、黒色
 奇数端子 : リン青銅 t=0.12mm
 偶数端子 : リン青銅 t=0.12mm
 HOUSING : LIQUID CRYSTAL POLYMER (LCP)、GLASS FILLED、UL94 V-0、NATURAL (WHITE)
 ACTUATOR : POLYAMIDE (PA)、GLASS FILLED、UL94 HB、BLACK
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
- メッキ仕様 PLATING
 端子 TERMINAL
 テール部: 金メッキ
 接点部: 金メッキ 0.1μm以上
 下地: ニッケルメッキ 1.0μm以上
 TAIL AREA : Gold PLATING
 CONTACT AREA : Gold PLATING 0.1μm MINIMUM
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
- 端子の平坦度は0.1mm以下とする
 COPLANALITY OF SOLDER TAILS: 0.1mmMAX.
- ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

CONNECTOR SERIES NO. 504740-**-09

REVISED EC NO: J2015-1144 DR: M. N. SANUMA 2015/03/06 CHK: K. TAKAHASHI 2015/04/13 APPR: Y. NOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17			
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.	
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001		1 OF 2	
ANGULAR	±1 °	MATERIAL NO.		SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参照基板レイアウト(マウント面)

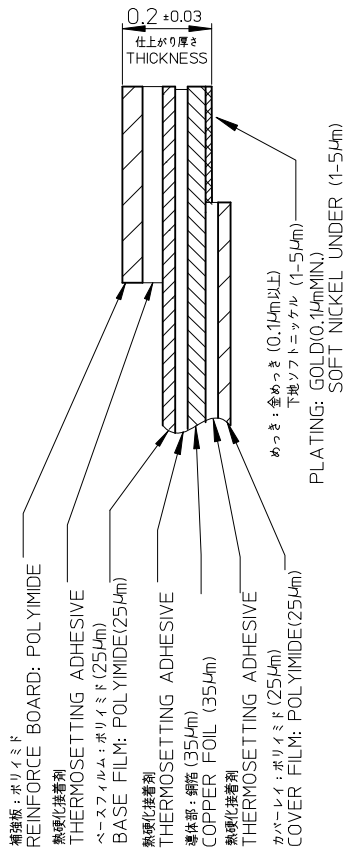
P.W.BOARD PATTERN
DIM.(REF)

推奨メタルマスク厚さ: 0.1mm

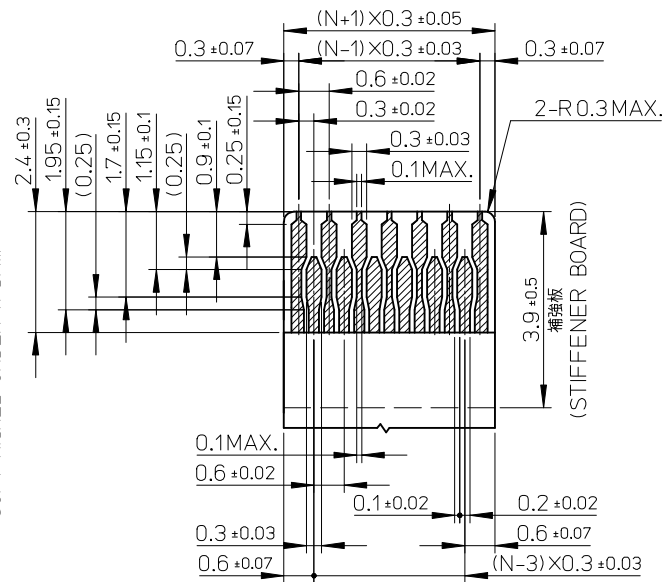
RECOMMENDED METAL MASK THICKNESS: 0.1mm

推奨開口率: 80%

APERTURE RATE: 80%



FPC構成推奨仕様
STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ: 0.20±0.03)

APPLY FPC RECOMMENDED DIM.

(THICKNESS: 0.20±0.03)

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強版側を推奨致します。
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

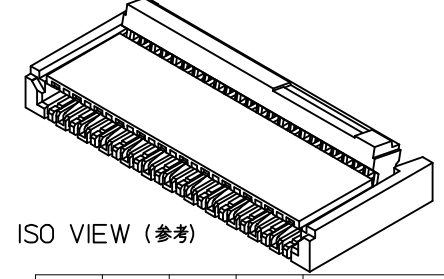
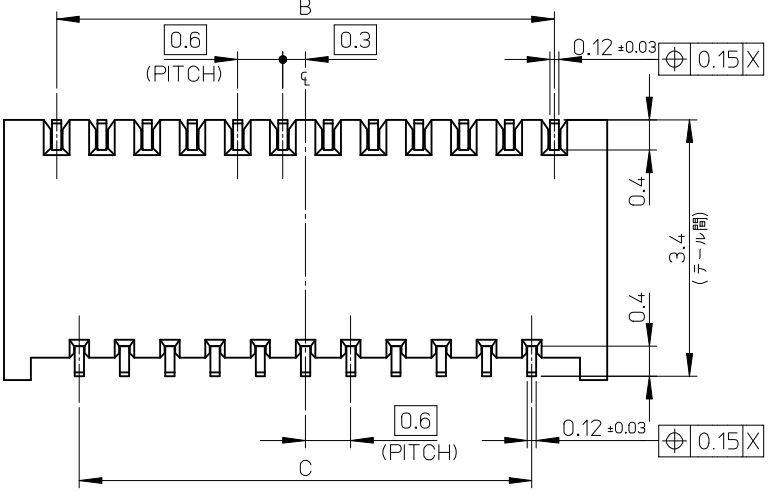
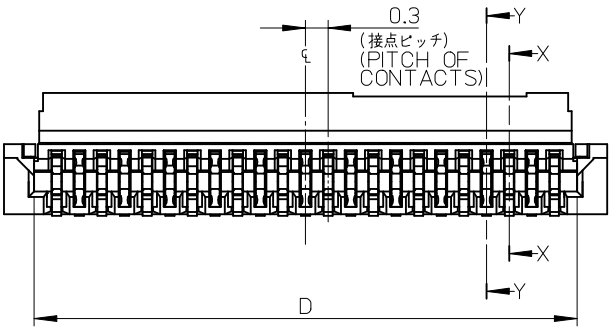
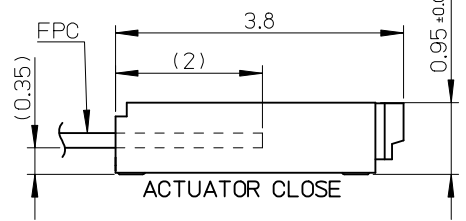
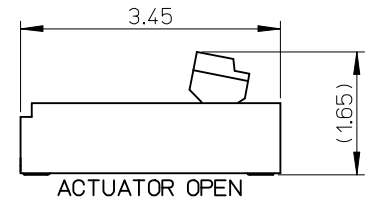
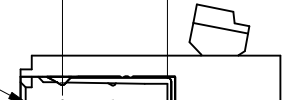
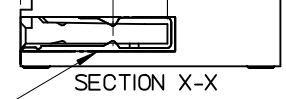
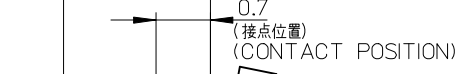
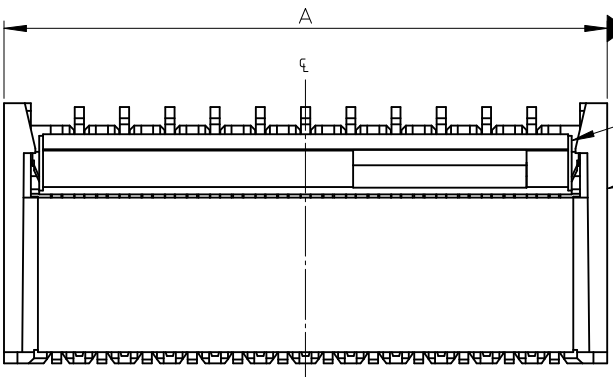
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

SEE SHEET 1 OF 2 EC NO: J2015-1144 DRAWN: SANUMA 2015/03/06 CHKD: TAKAHASHI 2015/04/13 APPR: YNOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE			
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY			
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex			
	1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17				
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001		2 OF 2		
ANGULAR ±1 °		MATERIAL NO.		SEE SHEET 1 OF 2				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

注記 NOTES

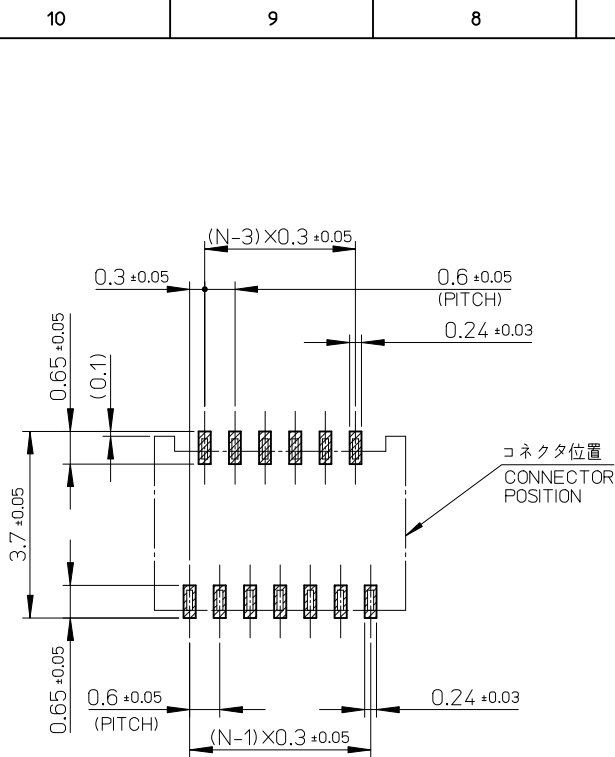
- 使用材料 MATERIALS
 ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94 V-0、ナチュラル (白色系)
 アクチュエータ: ポリアミド (PA)、ガラス充填、UL94 HB、黒色
 奇数端子 : リン青銅 t=0.12mm
 偶数端子 : リン青銅 t=0.12mm
 HOUSING : LIQUID CRYSTAL POLYMER (LCP)、GLASS FILLED、UL94 V-0、NATURAL (WHITE)
 ACTUATOR : POLYAMIDE (PA)、GLASS FILLED、UL94 HB、BLACK
 ODD TERMINAL : PHOSPHOR BRONZE t=0.12mm
 EVEN TERMINAL : PHOSPHOR BRONZE t=0.12mm
- メッキ仕様 PLATING
 端子 TERMINAL
 テール部: 金メッキ
 接点部: 金メッキ 0.1μm以上
 下地: ニッケルメッキ 1.0μm以上
 TAIL AREA : Gold PLATING
 CONTACT AREA : Gold PLATING 0.1μm MINIMUM
 UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
- 端子の平坦度は0.1mm以下とする
 COPLANALITY OF SOLDER TAILS: 0.1mmMAX.
- ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT



18.6	17.4	18.0	19.4	504740-6100	61
15.6	14.4	15.0	16.4	504740-5100	51
13.8	12.6	13.2	14.6	504740-4500	45
12.6	11.4	12.0	13.4	504740-4100	41
12.0	10.8	11.4	12.8	504740-3900	39
11.4	10.2	10.8	12.2	504740-3700	37
10.2	9.0	9.6	11.0	504740-3300	33
7.2	6.0	6.6	8.0	504740-2300	23
6.0	4.8	5.4	6.8	504740-1900	19
D	C	B	A	EMBOSSED TAPE	CIRCUITS
				ORDER NO. オーダー番号	

CONNECTOR SERIES NO. 504740-**-09

REVISED EC NO: J2015-1144 DR: M. N. SANUMA 2015/03/06 CHK: K. TAKAHASHI 2015/04/13 APPR: Y. NOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER 10 UNDER	±0.2	HIJIMA	2013/07/17			
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.			
30 OVER	±0.3	YNOGAWA	2014/03/05	SD-504740-001			
ANGULAR	±1 °	MATERIAL NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		1 OF 2			
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参照基板レイアウト(マウント面)

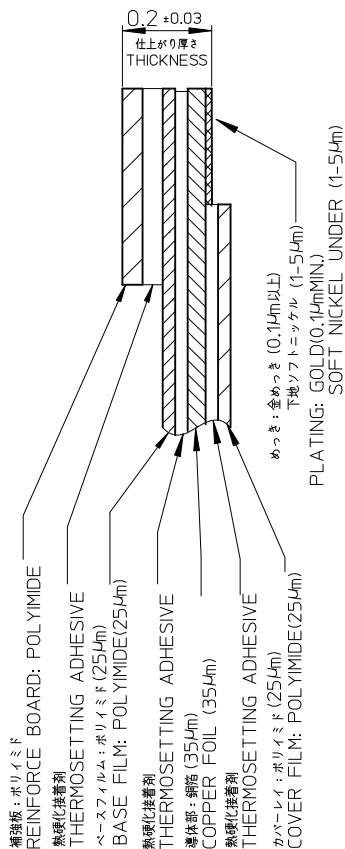
P.W. BOARD PATTERN
DIM.(REF)

推奨メタルマスク厚さ : 0.1mm

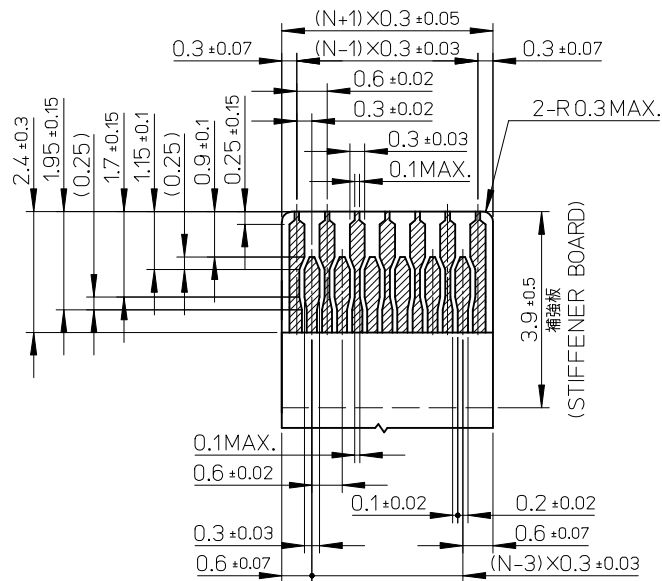
RECOMMENDED METAL MASK THICKNESS : 0.1mm

推奨開口率 : 80%

APERTURE RATE : 80%



FPC構成推奨仕様
STRUCTURE OF FPC



適合FPC推奨寸法

(仕上がり厚さ : 0.20 ± 0.03)

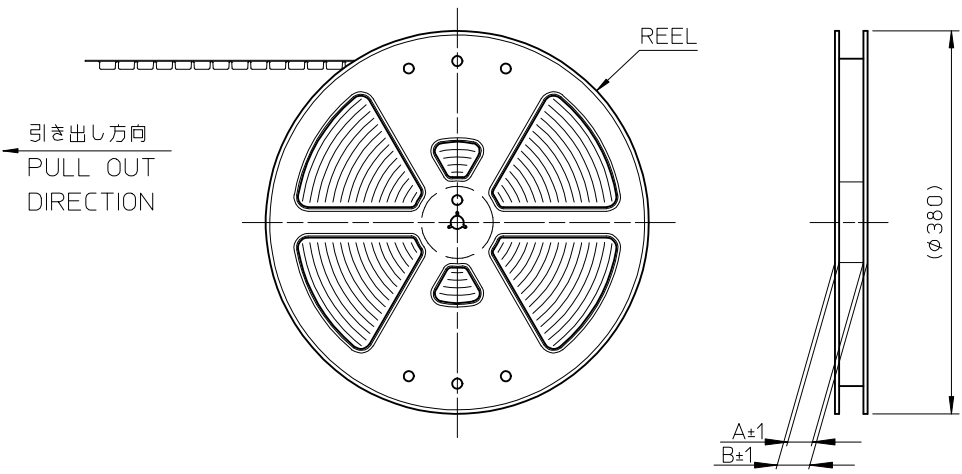
APPLY FPC RECOMMENDED DIM.
(THICKNESS : 0.20 ± 0.03)

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強版側を推奨致します。
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

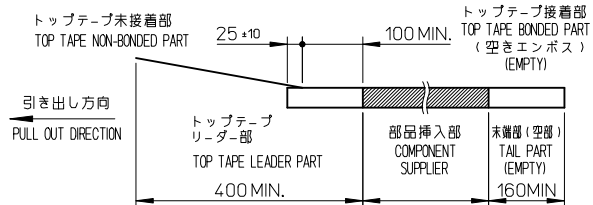
※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY			METRIC		
0.25	UNDER			±0.03	DRAWN BY	DATE	TITLE		
0.25	OVER	0.5	UNDER	±0.05	TONO	2013/07/17	0.3 FPC CONN. BACK FLIP HGT=0.95MM HOUSING ASSY		
0.5	OVER	1.0	UNDER	±0.1	CHECKED BY	DATE			
1.0	OVER	10	UNDER	±0.2	HIJIMA	2013/07/17			
10	OVER	30	UNDER	±0.25	APPROVED BY	DATE			
30	OVER			±0.3	YNOGAWA	2014/03/05			
ANGULAR ±1 °				MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE SHEET 1 OF 2		SD-504740-001		2 OF 2	
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



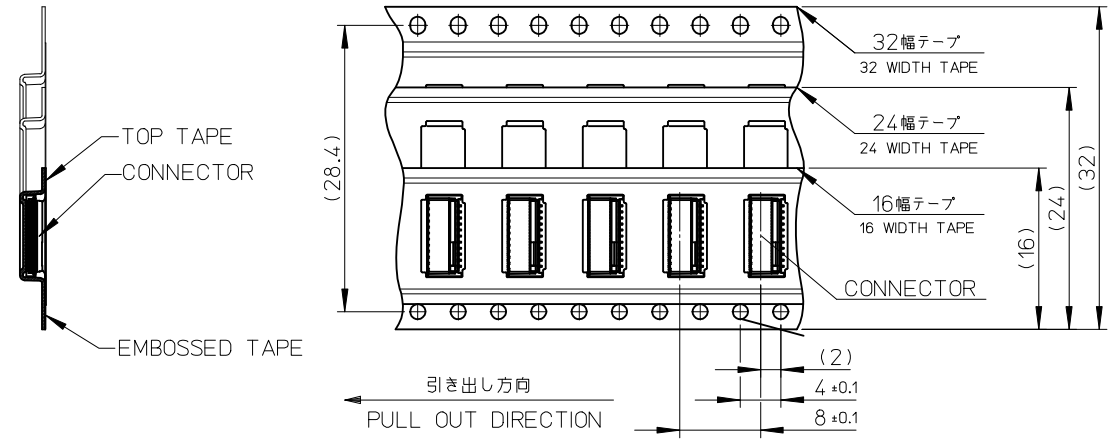
NOTES

- 製品詳細寸法については、図面 SD-504740-001をご参照下さい。
REFER TO THE SD-504740-001 ABOUT DIMENSIONS IN DETAIL.
- 梱包数量 : 5000 個/リール
NUMBER OF CONNECTORS : 5000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度については、IEC60286-3 に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>



32	37.4	33.4	504740-6100	61
			504740-5100	51
24	29.4	25.4	504740-4500	45
			504740-4100	41
			504740-3900	39
			504740-3700	37
			504740-3300	33
16	21.4	17.4	504740-2300	23
			504740-1900	19
テープ幅 TAPE WIDTH	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT
CONNECTOR SERIES NO.			504740-**-09	

エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSED TAPE

REVISED EC NO: J2015-1144 DRWN:NASUNUMA 2015/03/06 CHKD:KAKAHASHI 2015/04/13 APPR:YNOGAWA 2015/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:0	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE			
	0.25 OVER	0.5 UNDER	±0.05	TONO	2013/07/25	0.3 FPC CONN. BACK FLIP HGT=0.95MM EMBSTP PKG			
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex			
	1.0 OVER	30 UNDER	±0.2	HIIJIMA	2013/07/25	SD-504740-002			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SHEET NO.				
30 OVER		±0.3	YNOGAWA	2014/03/05	1 OF 1				
ANGULAR	±1 °		MATERIAL NO.		DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				